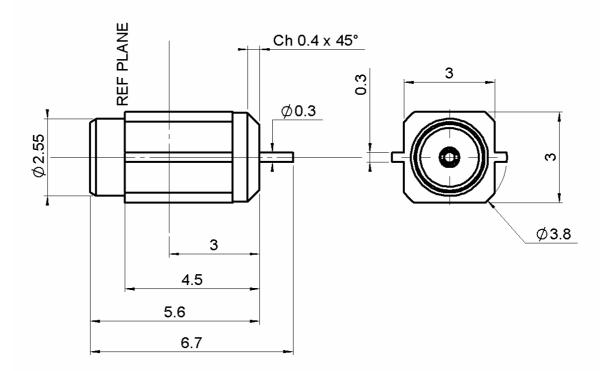
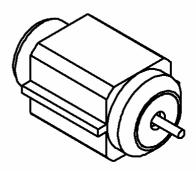
REEL OF 400

R199.005.800

Series: MC-CARD







All dimensions are in mm.

 COMPONENTS	MATERIALS	PLATINGS (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS -	BRASS BERYLLIUM COPPER - PTFE	GOLD 0.2 OVER NICKEL 2 GOLD 0.8 OVER NICKEL 2
-	-	-

Issue: 1101 F

In the effort to improve our products, we reserve the right to make changes judged to be



REEL OF 400

R199.005.800

Series: MC-CARD

PACKAGING

Standard	Unit	Other
400	'W' option	Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance 50Ω

Frequency **0-8** GHz

VSWR 1.15 + 0,0150 x F(GHz) Maxi

Insertion loss RF leakage - ($\sqrt{F(GHz)}$ dB Maxi - $\sqrt{F(GHz)}$ dB Maxi

RF leakage - (- F(GHz)) dB Voltage rating 170 Veff Maxi

 $\begin{array}{ccc} \text{Dielectric with standing voltage} & & \textbf{500} & \text{Veff mini} \\ \text{Insulation resistance} & & \textbf{5000} & \text{M}\Omega \text{ mini} \end{array}$

ENVIRONMENTAL

Operating temperature -65/+165 ° C

Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHERS CHARACTERISTICS

Assembly instruction

Others:

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

10 N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 5000 Cycles mini

Weight **0,2470** g

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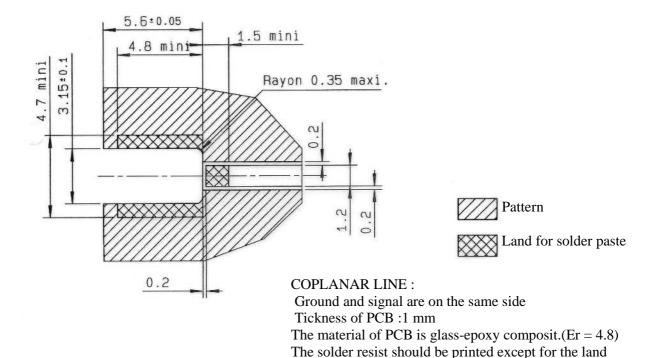


REEL OF 400

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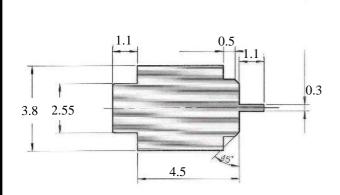
Series: MC-CARD

INFORMATIONS

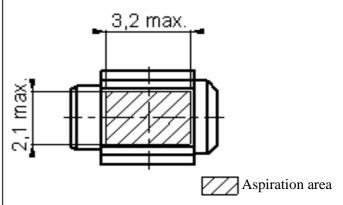


pattern on the PCB.

SHADOW OF RECEPTACLE FOR VIDEO CAMERA



ASPIRATION AREA



Issue: 1101 F

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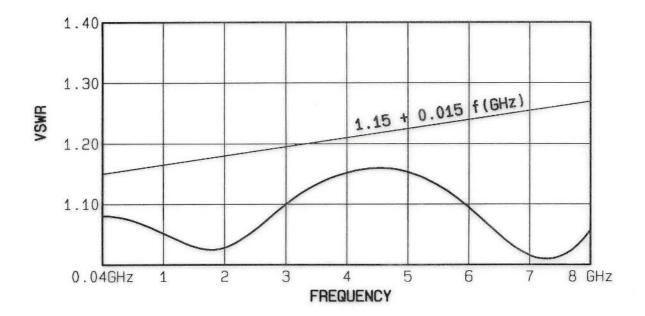


REEL OF 400

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Series : MC-CARD

R199 005 504 CONNECTED WITH R199 005 200



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REEL OF 400

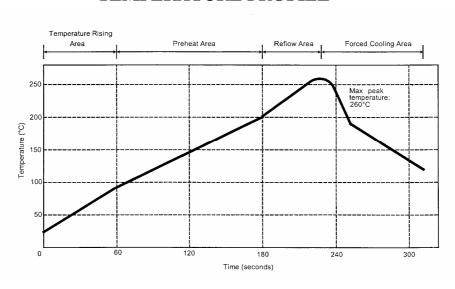
R199.005.800

Series: MC-CARD

SOLDER PROCEDURE

- 1. Deposition of solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of 150 microns (5.850 microinch). Verify that the edges of the zone are clean.
- Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
 Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. This process of soldering has been tested with convection oven. Below please find, the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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necessary.

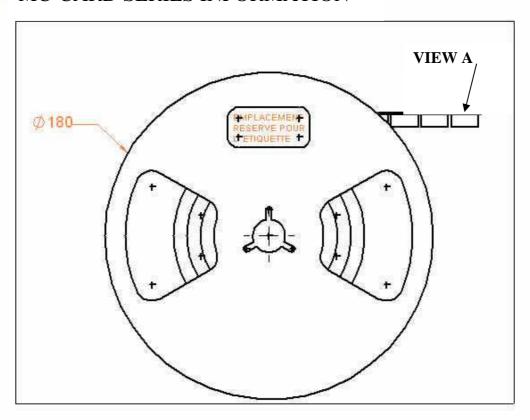


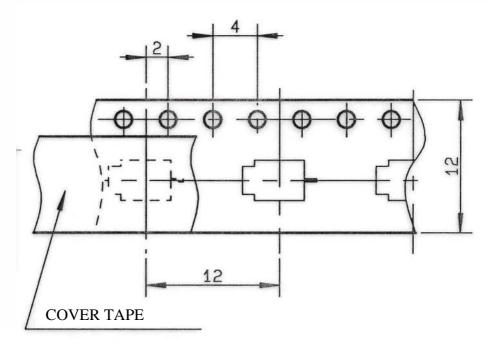
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Series: MC-CARD

MC-CARD SERIES INFORMATION





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